ABBOCIATION CONNECTING ELECTRONICS INDUSTRIES® International and Pa	IPC, Bannock	burn, Illinois. A	Il rights reserved untions.	nder both	This docume level parts, t	ent is a declar the declaratio	ration of n encon	f the substanc npasses all lov	es within wer leve	the manufact materials for	turer listed i which the n	tem. No nanufac	ote: if the turer has	item is an as engineering	sembly with low responsibility.	
	IPC Web Site for Information on IPC-1752 Standard Form Typ http://www.ipc.org/IPC-175x Distribute				e *	* Declaration Class * Class 6 - RoHS Yes/No, Homogeneous Mater					erials and M	ials and Mfg Information				
Supplier Information																
Company name*	Company unique ID			1	Unique ID Authority					Respons	Response Date*					
nsemi											2024-05-12					
Contact Name	Title - Conta	Title - Contact			Phone - Contact*					Email -	Email - Contact*					
Product-Env-Stewards	Product Enviro Compliance				NA					Produc	Product-Env-Stewards@onsemi.com					
uthorized Representative*	Title - Representative			Phone - Representative*				Email -	Email - Representative*							
Product-Env-Stewards	Product Enviro Compliance				NA				Produc	Product-Env-Stewards@onsemi.com						
Requester Item Number	Mfr Iter	n Number	Mfr Item Name			Effective Da	ate V	ersion	Manufacturing Site			Weight	*	UOM	Unit Type	
	N24C08	SUDTG	8Kb I2C SER EEPROM			2024-05-12			THB	ТНВ		11.479		mg	Each	
Aanufacturing Proccess Informa	ation													1	I	
Terminal Plating / Grid Array M	Iaterial '	Terminal Base	Alloy	loy J-STD-020 MSL		Peak Process		Body Temperature Max Time at Pea		ak Temperat	Temperature Number		f Reflow Cyc	les		
Precious metal (e.g. Ag,Au, NiPdAu) (no Sn)		CU Alloy 1		1		260		С	30	30		ds 3				
omments																
evel 1 - maximum time at peak temperat	ture during so	ldering is 10-3	0 seconds													
or more information regarding materia	l composition	please refer to	page 3													

RoHS Material Composition Declaration				Declaration Type *	Detailed						
Directive 2015/863/EU amending RoHS Directive 2011/65/EU	RoHS Definition: Quantity limit of 0.01% by mass (100 PPM) in homogeneous material for Cadmium and quantity limit of 0.1% by mass (1000 PPM) in homogeneous material for: Lead (Pb), Mercury (Hg), Hexavalent Chromium (Cr6+), Polybrominated Biphenyls (PBB), Polybrominated Diphenyl Ethers (PBDE), and Bis(2-ethylhexyl) phthalate (DEHP), Benzyl-butyl phthalate (BBP), Dibutyl phthalate (DBP), Disobutyl phthalate (DIBP).										
cadmium, hexavalentchromium, polybrominate contains a RoHS restricted substance inexcess encompass all such components. Supplier certif as of the date that Supplier completes this form Company acknowledges that Supplier may hav independently verified information provided by certification in this paragraph. If the Company a	ed biphenyls and/or polybrominated dip of an applicable quantity limit, please ir ies that it gathered the information it pro- .Supplier acknowledges that Company e relied on informationprovided by othe v others, Supplier agrees that, at a minin and the Supplier enter into a written agre pource of the Supplier's liability and the	henyl ethers (each a " ndicate below which, i ovides in this form us will rely on this certifiers in completing this num, itssuppliers have eement with respect to Company's remedies	RoHS restricted substance") in exce if any, RoHS exemption you believe ing appropriate methods to ensure if ication in determining the complian form, and that Supplier may not have e provided certifications regarding the to the identified part, the terms and cc for issues that arise regarding inform	ce of its products with European Union membe	ove. If a homogeneous material within the part er level components, the declaration shall l correct to the best of its knowledge and belief, r state laws that implement the RoHS Directive. wever, in situations where Supplier has not tions are at least as comprehensive as the anty rights and/or remedies provided as part of						
RoHS Declaration * 1 - Item(s)	does not contain RoHS restricted substa	on above	Supplier Acceptance	* Accepted							
Exemption: If the declared item does not con applicable exemptions.	ntain RoHS restricted substances per	the definition above	except for defined RoHS exempti	ons, then select the corresponding response i	n the RoHS Declaration above and choose all						
Exemption List Version	EL-2011/534/EU										
Declaration Signature											
Instructions: Complete all of the required fin Requester) and click on Submit Form to have	elds on all pages of this form. Select the form returned to the Requester	he "Accepted" on th	e Supplier Acceptance drop-down	. This will display the signature area. Digital	lly sign the declaration (if required by the						
Supplier Digital Signature Ra	stislav Drska	Le									

Homogeneous Material Composition Declaration for Electronic Products

SubItem Instructions: The presence of any JIG Level A or B substances must be declared. [1] indicate the subpart in which the substance is located, [2] provide a description of the homogeneous material [3], enter the weight of the homogeneous material.

Homogeneous Material	Weight	Unit of Measure	Level	Substance	CAS	Exempt	Weight	Unit of Measure
Die	0.15	mg	Supplier	Silicon (Si)	7440-21-3		0.15	mg
Die Attach Tape	0.019	mg	Supplier	Oxirane, (chloromethyl)-, homopolymer	24969-06-0		0.0029	mg
			Supplier	2-Propenoic acid, 2-methyl-, polymer with butyl 2-propenoate and methyl 2- methyl-2-propenoate	25035-69-2		0.0029	mg
			Supplier	Proprietary	Proprietary Data	oprietary Data		mg
			Supplier	Silica Amorphous (SiO2)	7631-86-9		0.0085	mg
			Supplier	Phenolic Resin (Novolac)	9003-35-4		0.0029	mg
Lead Frame	4.7	mg	Supplier	Zinc (Zn)	7440-66-6		0.0056	mg
			Supplier	Iron (Fe)	7439-89-6		0.1104	mg
			Supplier	Copper (Cu)	7440-50-8		4.5825	mg
			Supplier	Phosphorus (P)	7723-14-0		0.0014	mg
Mold Compound-Black	6.5	mg		Epoxy resin	proprietary data		0.325	mg
			Supplier	Phenolic Resin	Proprietary Data		0.13	mg
			Supplier	Ortho Cresol Novolac Resin	29690-82-2		0.1625	mg
			Supplier	Carbon Black (C)	1333-86-4		0.0325	mg
			Supplier	Fused Silica (SiO2)	60676-86-0		5.85	mg
Plating	0.09	mg	Supplier	Palladium (Pd)	7440-05-3		0.0022	mg
			В	Nickel (Ni)	7440-02-0		0.0792	mg
			Supplier	Gold (Au)	7440-57-5		0.0086	mg
Wire Bond - Au	0.02	mg	Supplier	Gold (Au)	7440-57-5		0.02	mg